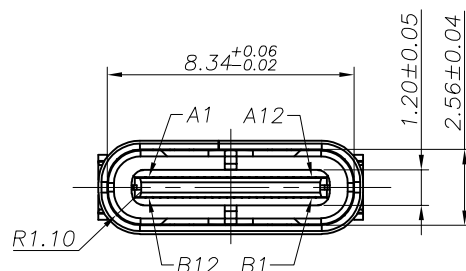
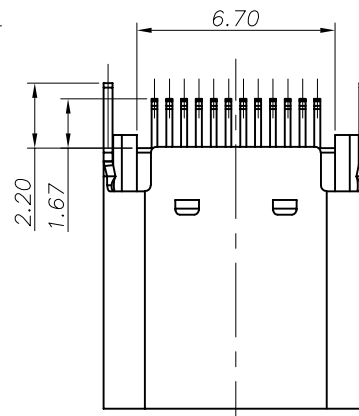
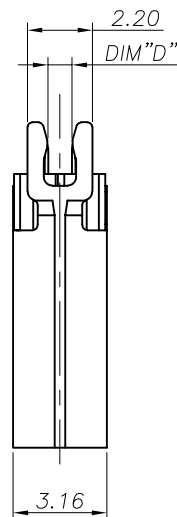
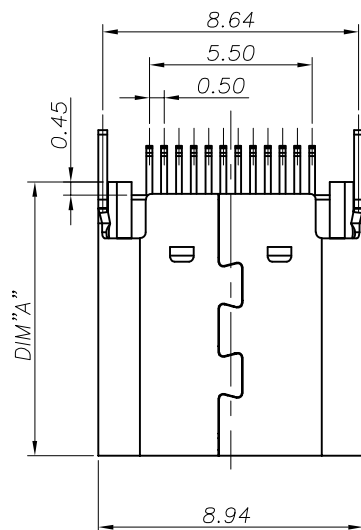
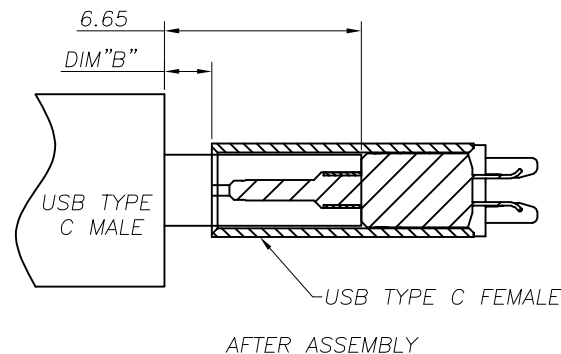
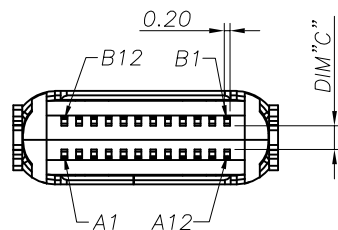


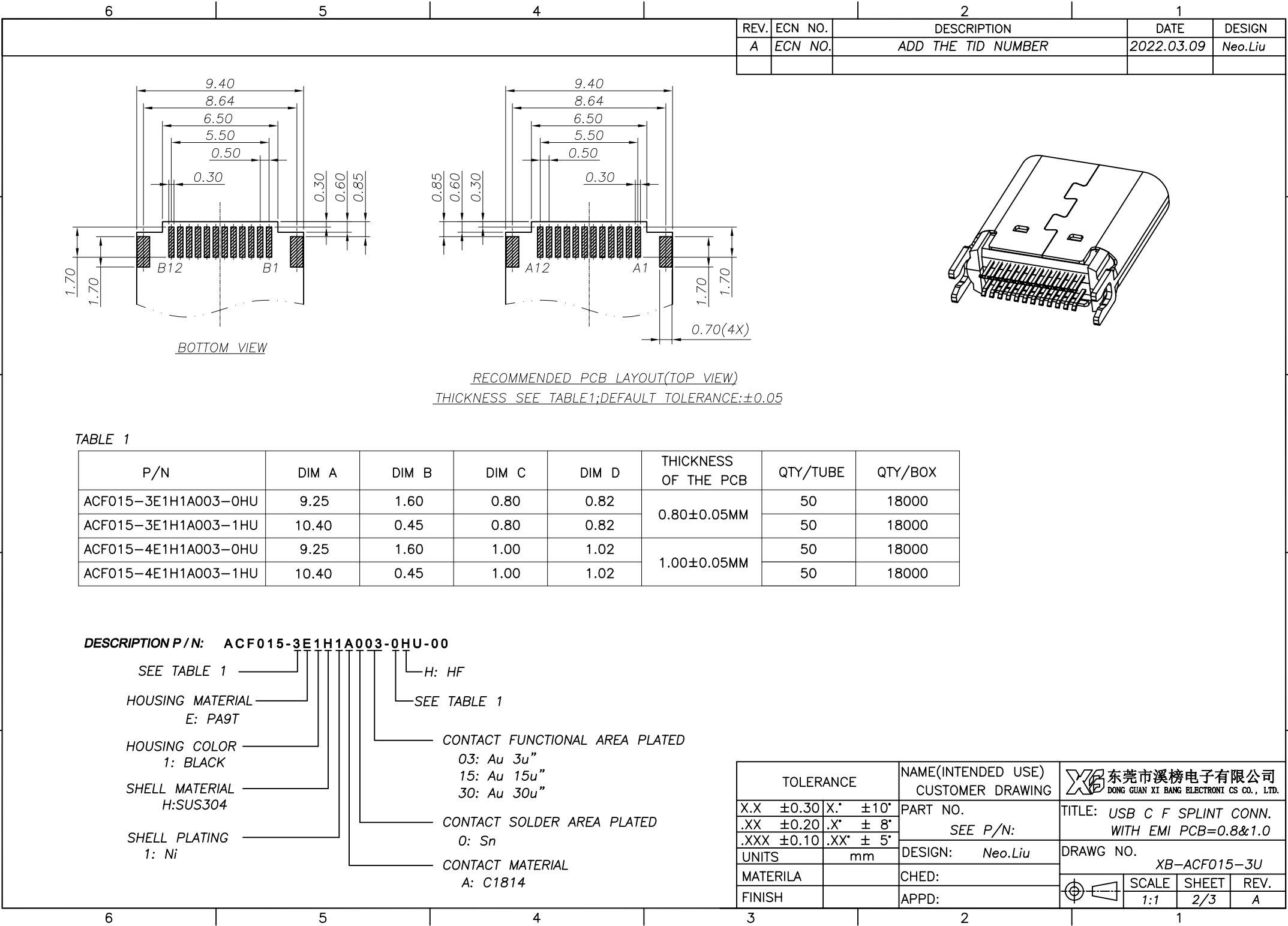
REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
A	ECN NO.	ADD THE TID NUMBER	2022.03.09	Neo.Liu

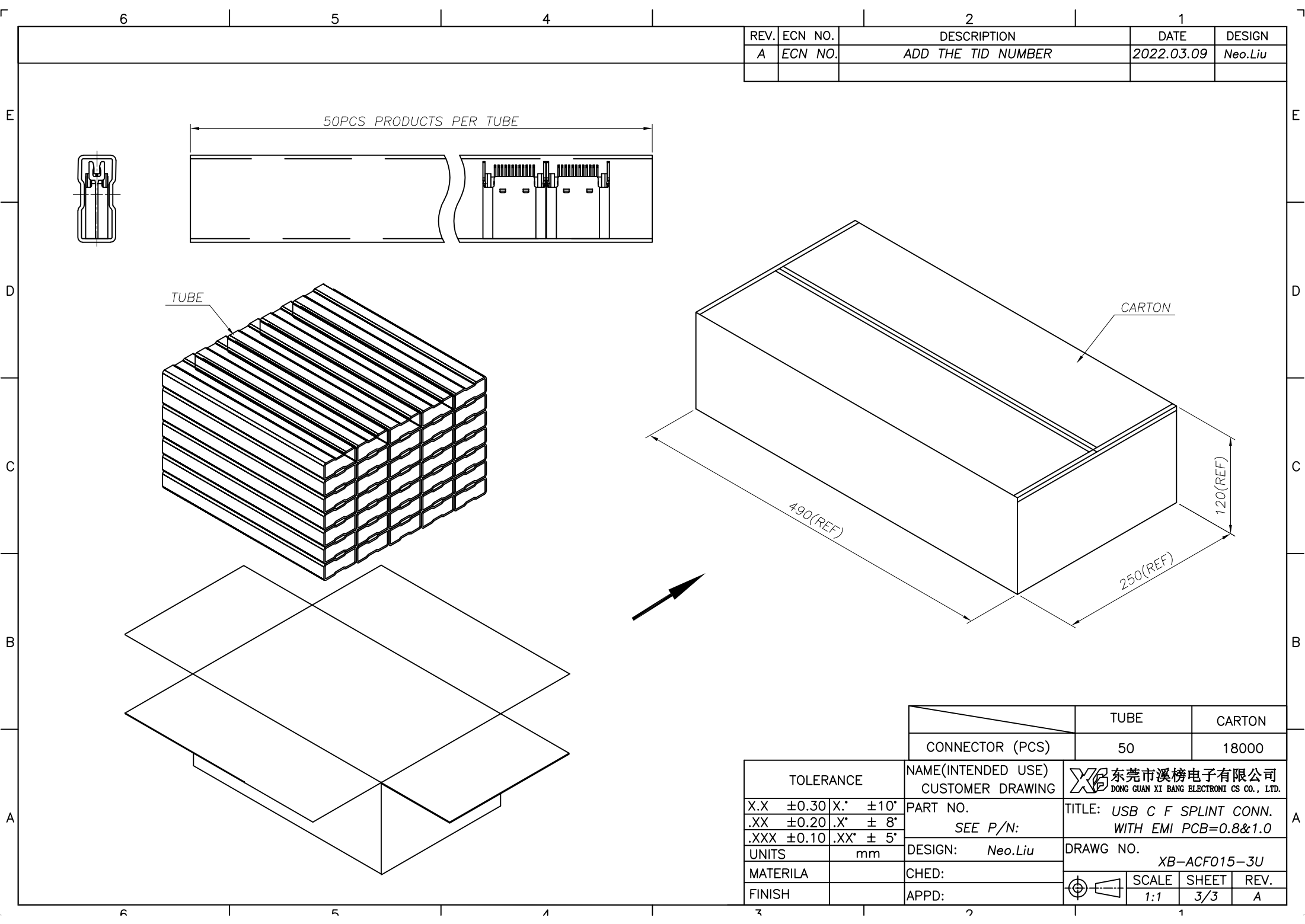


NOTE:
1.MATERIAL SPECIFICATION:
1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
2.CONTACTS: COPPER ALLOY(C1814)
3.MID PLATE: STAINLESS STEEL(SUS301)
4.FRONT SHELL: STAINLESS STEEL(SUS304)
5.EMI PLATE: STAINLESS STEEL(SUS304)
2.PLATING SPECIFICATION:
2-1.TERMINAL:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
2-2.FRONT SHELL:
Ni 30u" MIN. UNDER PLATED OVER ALL.
2-3.MID PLATE&EMI PLATE:
CLEAR ONLY
3.MECHANICAL PERFORMANCE,
3-1.INSERTION FORCE: 0.5~2.0kgf.
3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
3-3.DURABILITY: 10000 CYCLES.
4.ELECTRICAL PERFORMANCE,
4-1. CURRENT RATING:5.0A
VOLTAGE RATING:5.0V
4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
4-3.INSULATION RESISTANCE: 100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25°C~+85°C.
6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.
7.TID NUMBER:7231

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TXp1	TXn1	Vbus	CC1	D+	D-	SBU1	Vbus	RXn2	RXp2	GND
GND	RXp1	RXn1	Vbus	SBU2	D-	D+	CC2	Vbus	TXn2	TXp2	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

TOLERANCE		NAME(INTENDED USE) CUSTOMER DRAWING	 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONI CS CO., LTD.			
X.X ±0.30	X.* ±10°	PART NO.	TITLE: USB C F SPLINT CONN. WITH EMI PCB=0.8&1.0			
.XX ±0.20	.X* ± 8°	SEE P/N:				
.XXX ±0.10	.XX* ± 5°					
UNITS	mm	DESIGN: Neo.Liu	DRAWG NO.			
			XB-ACF015-3U			
MATERILA		CHED:				
FINISH		APPD:		SCALE 1:1	SHEET 1/3	REV. A





REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
A	ECN NO.	ADD THE TID NUMBER	2022.03.09	Neo.Liu

	TUBE	CARTON
CONNECTOR (PCS)	50	18000

TOLERANCE		NAME(INTENDED USE) CUSTOMER DRAWING	XB 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.		
X.X ±0.30	X.* ±10°	PART NO.	TITLE: USB C F SPLINT CONN. WITH EMI PCB=0.8&1.0		
.XX ±0.20	.X.* ± 8°	SEE P/N:			
.XXX ±0.10	.XX.* ± 5°	DESIGN: Neo.Liu	DRAWG NO. XB-ACF015-3U		
UNITS	mm	CHED:			
MATERILA		APPD:			
FINISH					



SCALE	SHEET	REV.
1:1	3/3	A